Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® microAptiv™
Core Size	32-Bit Single-Core
Speed	25MHz
Connectivity	IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, I²S, POR, PWM, WDT
Number of I/O	16
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 11x10/12b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mm0016gpl020-e-ss

1.0 DEVICE OVERVIEW

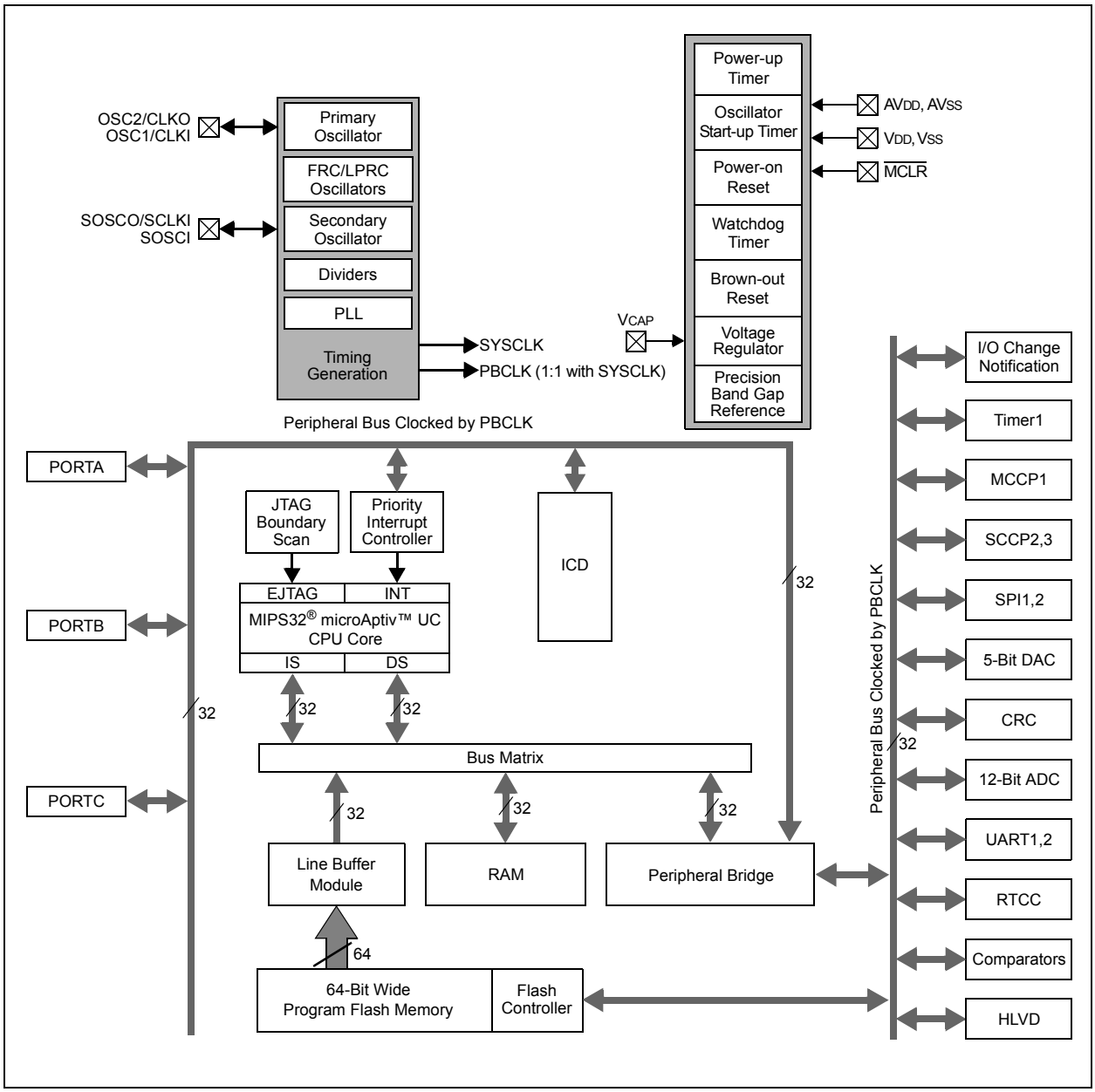
Note: This data sheet summarizes the features of the PIC32MM0064GPL036 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32). The information in this data sheet supersedes the information in the FRM.

This data sheet contains device-specific information for the PIC32MM0064GPL036 family devices.

Figure 1-1 illustrates a general block diagram of the core and peripheral modules in the PIC32MM0064GPL036 family of devices.

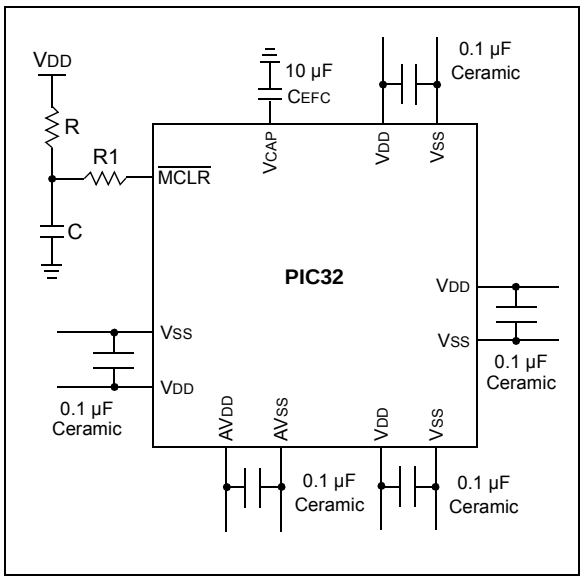
Table 1-1 lists the pinout I/O descriptions for the pins shown in the device pin tables.

FIGURE 1-1: PIC32MM0064GPL036 FAMILY BLOCK DIAGRAM



NOTES:

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



2.2.1 BULK CAPACITORS

The use of a bulk capacitor is recommended to improve power supply stability. Typical values range from 4.7 µF to 47 µF. This capacitor should be located as close to the device as possible.

2.3 Master Clear ($\overline{MCLR}$) Pin

The $\overline{MCLR}$ pin provides for two specific device functions:

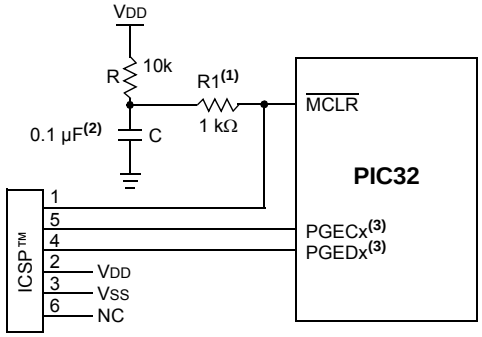
- Device Reset
- Device Programming and Debugging

Pulling The $\overline{MCLR}$ pin low generates a device Reset. Figure 2-2 illustrates a typical $\overline{MCLR}$ circuit. During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{MCLR}$ pin. Consequently, specific voltage levels (V_{IH} and V_{IL}) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as illustrated in Figure 2-2, it is recommended that the capacitor, C, be isolated from the $\overline{MCLR}$ pin during programming and debugging operations.

Place the components illustrated in Figure 2-2 within one-quarter inch (6 mm) from the $\overline{MCLR}$ pin.

FIGURE 2-2: EXAMPLE OF $\overline{MCLR}$ PIN CONNECTIONS(1,2,3)



Note 1: $470\Omega \leq R1 \leq 1\ k\Omega$ will limit any current flowing into $\overline{MCLR}$ from the external capacitor, C, in the event of $\overline{MCLR}$ pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{MCLR}$ pin V_{IH} and V_{IL} specifications are met without interfering with the debug/programmer tools.

2: The capacitor can be sized to prevent unintentional Resets from brief glitches or to extend the device Reset period during POR.

3: No pull-ups or bypass capacitors are allowed on active debug/program PGECx/PGEDx pins.

2.4 Capacitor on Internal Voltage Regulator (V_{CAP})

A low-ESR (<1 Ohm) capacitor is required on the V_{CAP} pin, which is used to stabilize the internal voltage regulator output. The V_{CAP} pin must not be connected to V_{DD} and must have a C_{EFC} capacitor, with at least a 6V rating, connected to ground. The type can be ceramic or tantalum. The recommended value of the C_{EFC} capacitor is 10 µF. On the printed circuit board, it should be placed as close to the V_{CAP} pin as possible. If the board is experiencing high-frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to this capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF.

4.0 MEMORY ORGANIZATION

PIC32MM microcontrollers provide 4 Gbytes of unified virtual memory address space. All memory regions, including program, data memory, SFRs and Configuration registers, reside in this address space at their respective unique addresses. The data memory can be made executable, allowing the CPU to execute code from data memory.

Key features include:

- 32-Bit Native Data Width
- Separate Boot Flash Memory (BFM) for Protected Code
- Robust Bus Exception Handling to Intercept Runaway Code
- Simple Memory Mapping with Fixed Mapping Translation (FMT) Unit

The PIC32MM0064GPL036 family devices implement two address spaces: virtual and physical. All hardware resources, such as program memory, data memory and peripherals, are located at their respective physical addresses. Virtual addresses are exclusively used by the CPU to fetch and execute instructions. Physical addresses are used by peripherals, such as Flash controllers, that access memory independently of the CPU.

The virtual address space is divided into two segments of 512 Mbytes each, labeled kseg0 and kseg1. The Program Flash Memory (PFM) and Data RAM Memory (DRM) are accessible from either kseg0 or kseg1, while the Boot Flash Memory (BFM) and peripheral SFRs are accessible only from kseg1.

The Fixed Mapping Translation (FMT) unit translates the memory segments into corresponding physical address regions. Figure 4-1 through Figure 4-3 illustrate the fixed mapping scheme, implemented by the PIC32MM0064GPL036 family core, between the virtual and physical address space.

The mapping of the memory segments depends on the CPU error level, set by the ERL bit in the CPU STATUS Register (SR). Error level is set (ERL = 1) by the CPU on a Reset, Soft Reset or NMI. In this mode, the CPU can access memory by the physical address. This mode is provided for compatibility with other MIPS® processor cores that use a TLB-based MMU. The C start-up code clears the ERL bit to zero, so that when application software starts up, it sees the proper virtual to physical memory mapping.

4.1 Alternate Configuration Bits Space

Every Configuration Word has an associated Alternate Word (designated by the letter A as the first letter in the name of the word). During device start-up, Primary Words are read, and if uncorrectable ECC errors are found, the BCFGERR (RCON<27>) flag is set and Alternate Words are used. If uncorrectable ECC errors are found in Primary and Alternate Words, the BCFGFAIL (RCON<26>) flag is set, and the default configuration is used. The Primary Configuration bits area is located at the address range, from 0x1FC01780 to 0x1FC017E8. The Alternate Configuration bits area is located at the address range, from 0x1FC01700 to 0x1FC01768.

REGISTER 5-1: NVMCON: NVM PROGRAMMING CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0, HC	R/W-0	R-0, HS, HC	R-0, HS, HC	r-0	U-0	U-0	U-0
	WR(1,4)	WREN(1)	WRERR(1,2)	LVDERR(1,2)	—	—	—	—
7:0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	NVMOP<3:0>(3)			

Legend:	HS = Hardware Settable bit	HC = Hardware Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	r = Reserved bit

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **WR:** Write Control bit(1,4)
This bit cannot be cleared and can be set only when WREN = 1, and the unlock sequence has been performed.
1 = Initiates a Flash operation
0 = Flash operation is complete or inactive

bit 14 **WREN:** Write Enable bit(1)
1 = Enables writes to the WR bit and disables writes to the NVMOP<3:0> bits
0 = Disables writes to the WR bit and enables writes to the NVMOP<3:0> bits

bit 13 **WRERR:** Write Error bit(1,2)
This bit can be cleared only by setting the NVMOP<3:0> bits = 0000 and initiating a Flash operation.
1 = Program or erase sequence did not complete successfully
0 = Program or erase sequence completed normally

bit 12 **LVDERR:** Low-Voltage Detect Error bit(1,2)
This bit can be cleared only by setting the NVMOP<3:0> bits = 0000 and initiating a Flash operation.
1 = Low voltage is detected (possible data corruption if WRERR is set)
0 = Voltage level is acceptable for programming

bit 11 **Reserved:** Maintain as '0'

bit 10-4 **Unimplemented:** Read as '0'

Note 1: These bits are only reset by a Power-on Reset (POR) and are not affected by other Reset sources.
2: These bits are cleared by setting NVMOP<3:0> = 0000 and initiating a Flash operation (i.e., WR).
3: NVMOP<3:0> bits are write-protected if the WREN bit is set.
4: Writes to the WR bit require an unlock sequence. Refer to **Section 5.1 "Flash Controller Registers Write Protection"** for details.

REGISTER 7-7: IPCx: INTERRUPT PRIORITY CONTROL REGISTER x(1) (CONTINUED)

bit 12-10 **IP1<2:0>:** Interrupt Priority bits
111 = Interrupt priority is 7
•
•
•
010 = Interrupt priority is 2
001 = Interrupt priority is 1
000 = Interrupt is disabled

bit 9-8 **IS1<1:0>:** Interrupt Subpriority bits
11 = Interrupt subpriority is 3
10 = Interrupt subpriority is 2
01 = Interrupt subpriority is 1
00 = Interrupt subpriority is 0

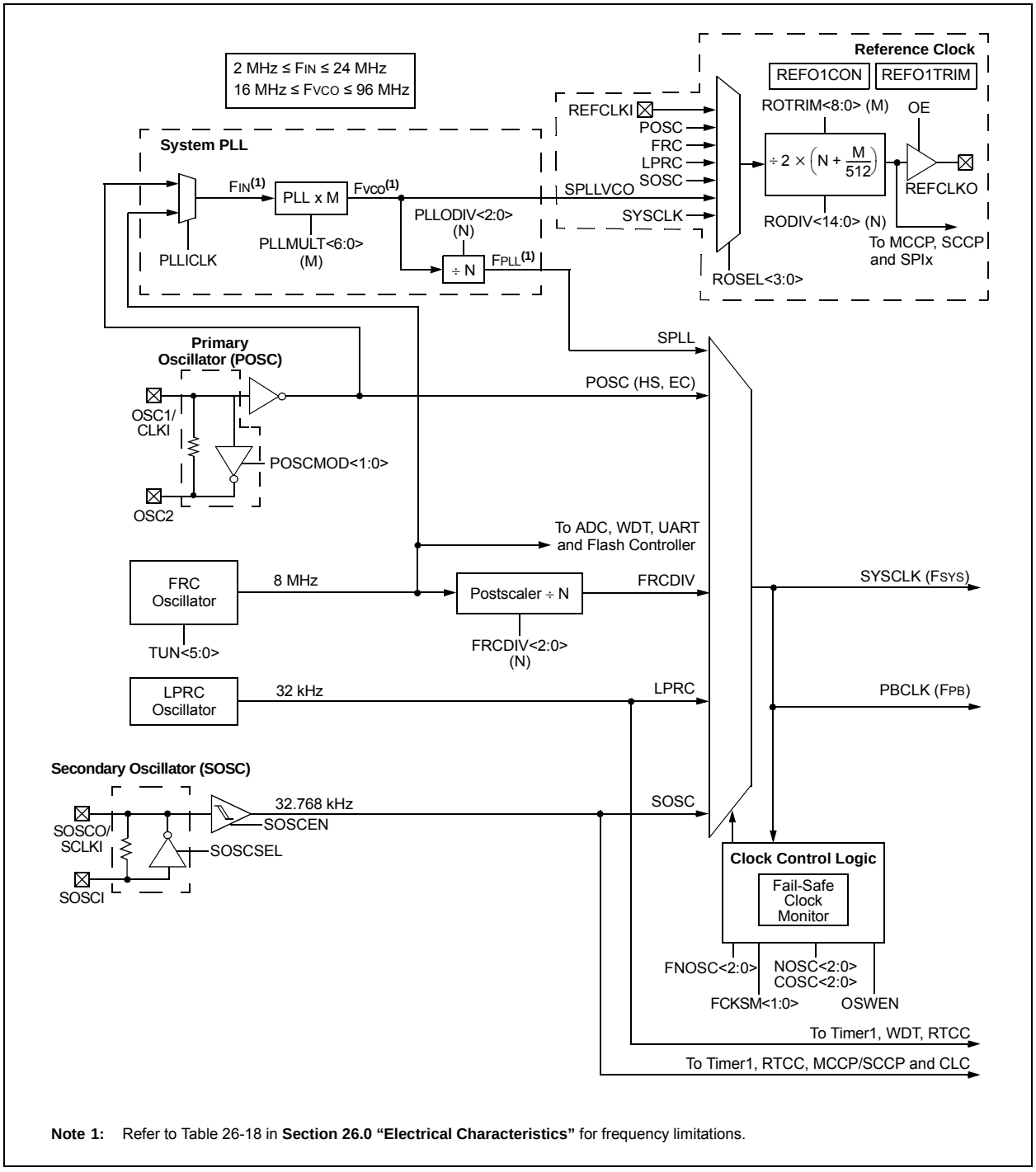
bit 7-5 **Unimplemented:** Read as '0'

bit 4-2 **IP0<2:0>:** Interrupt Priority bits
111 = Interrupt priority is 7
•
•
•
010 = Interrupt priority is 2
001 = Interrupt priority is 1
000 = Interrupt is disabled

bit 1-0 **IS0<1:0>:** Interrupt Subpriority bits
11 = Interrupt subpriority is 3
10 = Interrupt subpriority is 2
01 = Interrupt subpriority is 1
00 = Interrupt subpriority is 0

Note 1: This register represents a generic definition of the IPCx register. Refer to Table 7-3 for the exact bit definitions.

FIGURE 8-1: PIC32MM0064GPL036 FAMILY OSCILLATOR DIAGRAM



Note 1: Refer to Table 26-18 in **Section 26.0 "Electrical Characteristics"** for frequency limitations.

10.0 TIMER1

Note: This data sheet summarizes the features of the PIC32MM0064GPL036 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 14. "Timers"** (DS60001105) in the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32). The information in this data sheet supersedes the information in the FRM.

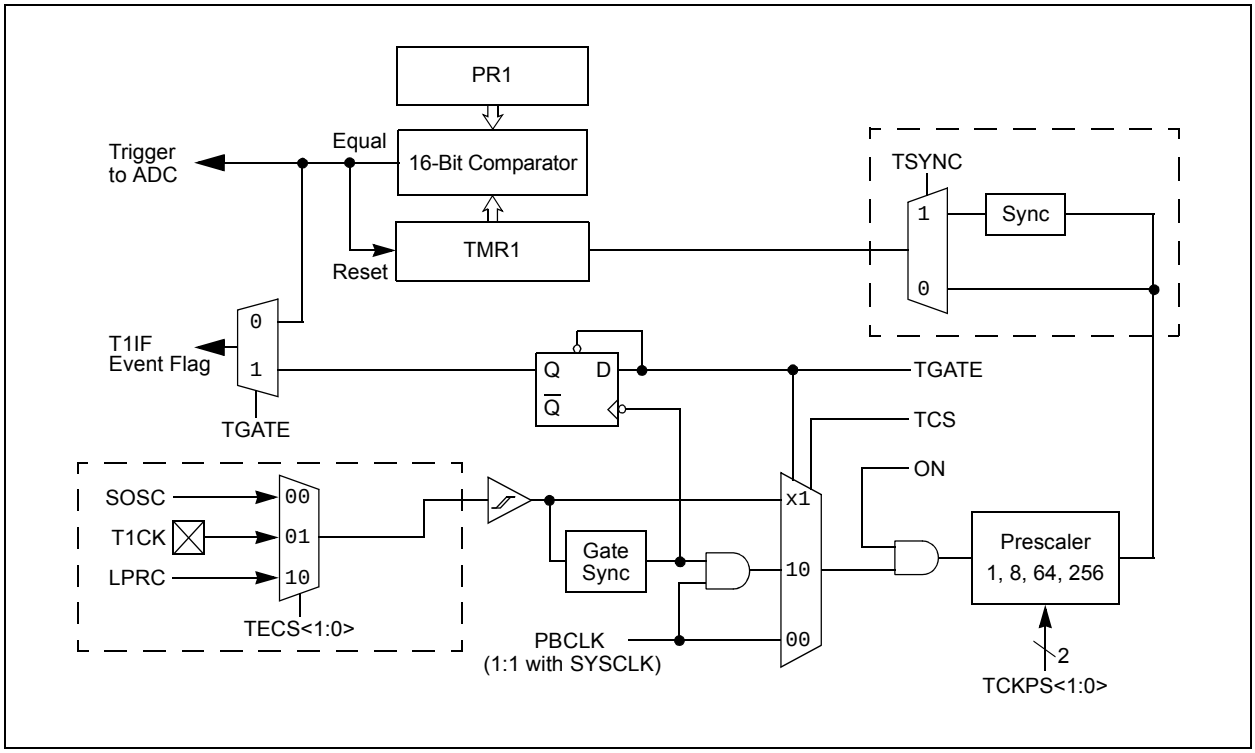
PIC32MM0064GPL036 family devices feature one synchronous/asynchronous 16-bit timer that can operate as a free-running interval timer for various timing applications and counting external events. This timer can be clocked from different sources, such as the Peripheral Bus Clock (PBCLK, 1:1 with SYSCLK), Secondary Oscillator (SOSC), T1CK pin or LPRC oscillator.

The following modes are supported by Timer1:

- Synchronous Internal Timer
- Synchronous Internal Gated Timer
- Synchronous External Timer
- Asynchronous External Timer

The timer has a selectable clock prescaler and can operate in Sleep and Idle modes.

FIGURE 10-1: TIMER1 BLOCK DIAGRAM



14.0 UNIVERSAL ASYNCHRONOUS RECEIVER TRANSMITTER (UART)

Note: This data sheet summarizes the features of the PIC32MM0064GPL036 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 21. "UART"** (DS61107) in the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32). The information in this data sheet supersedes the information in the FRM.

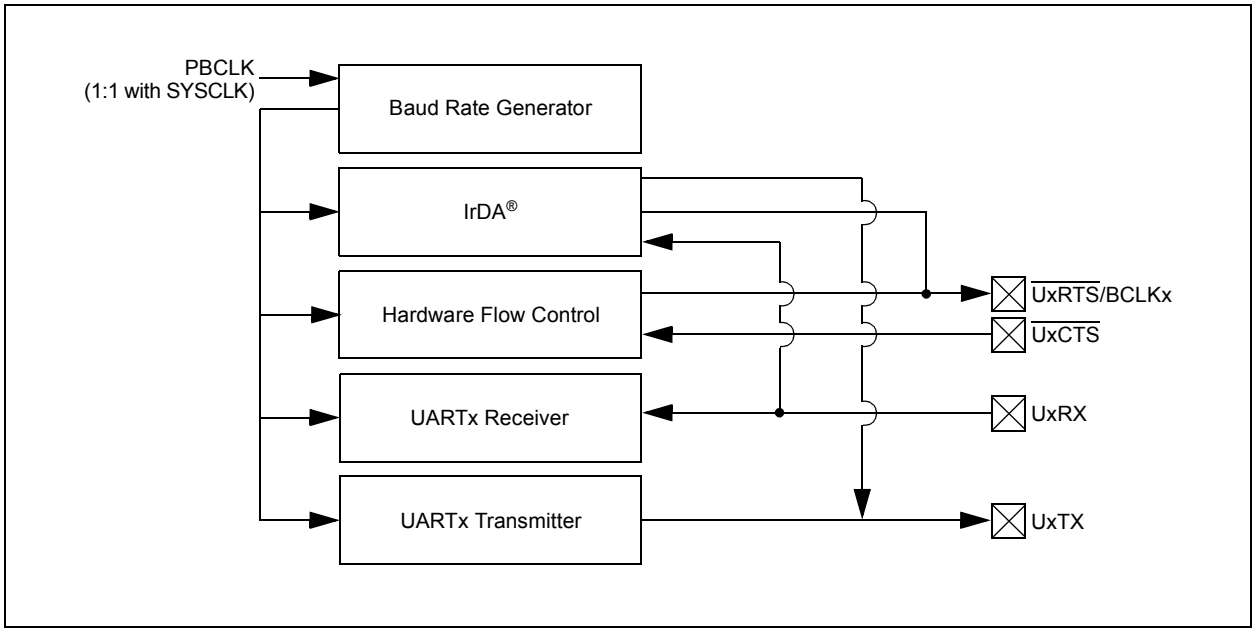
The UART module is one of the serial I/O modules available in the PIC32MM0064GPL036 family devices. The UART is a full-duplex, asynchronous communication channel that communicates with peripheral devices and personal computers through protocols, such as RS-232, RS-485, LIN/J2602 and IrDA®. The module also supports the hardware flow control option with the $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins, and also includes an IrDA encoder and decoder.

The primary features of the UART module are:

- Full-Duplex, 8-Bit or 9-Bit Data Transmission
- Even, Odd or No Parity Options (for 8-bit data)
- One or Two Stop Bits
- Hardware Auto-Baud Feature
- Hardware Flow Control Option
- Fully Integrated Baud Rate Generator (BRG) with 16-Bit Prescaler
- Baud Rates Ranging from 47.7 bps to 6.26 Mbps at 25 MHz
- 8-Level Deep First-In-First-Out (FIFO) Transmit Data Buffer
- 8-Level Deep FIFO Receive Data Buffer
- Parity, Framing and Buffer Overrun Error Detection
- Support for Interrupt Only on Address Detect (9th bit = 1)
- Separate Transmit and Receive Interrupts
- Loopback mode for Diagnostic Support
- LIN/J2602 Protocol Support
- IrDA Encoder and Decoder with 16x Baud Clock Output for External IrDA Encoder/Decoder Support
- Supports Separate UART Baud Clock Input
- Ability to Continue to Run when a Receive Overflow (ROV) Condition Exists
- Ability to Run and Receive Data during Sleep mode

Figure 14-1 illustrates a simplified block diagram of the UART module.

FIGURE 14-1: UARTx SIMPLIFIED BLOCK DIAGRAM



15.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

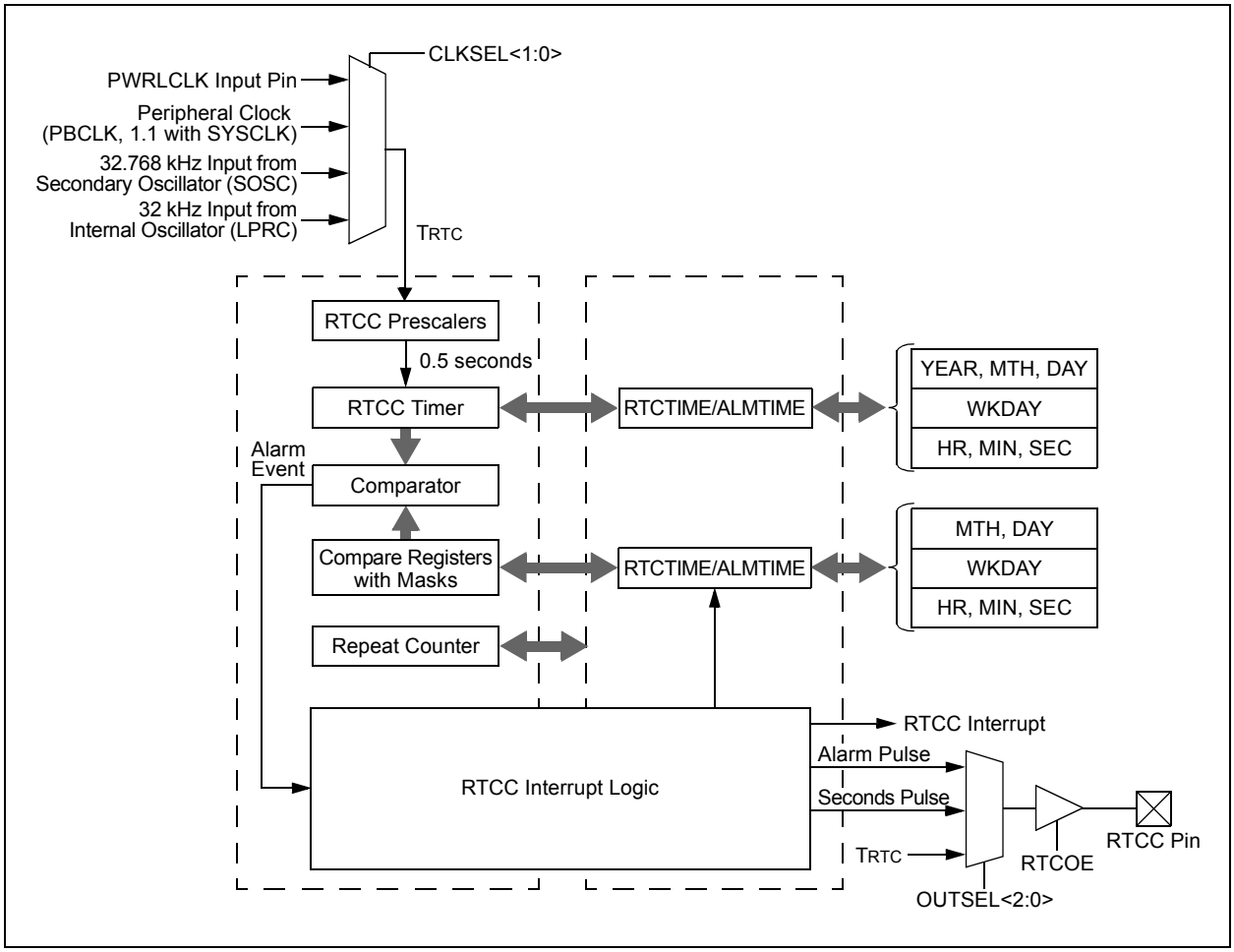
Note:	This data sheet summarizes the features of the PIC32MM0064GPL036 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 28. "RTCC with Timestamp"** (DS60001362) in the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32). The information in this data sheet supersedes the information in the FRM.

The RTCC module is intended for applications in which accurate time must be maintained for extended periods of time with minimal or no CPU intervention. Low-power optimization provides extended battery lifetime while keeping track of time.

Key features of the RTCC module are:

- Time: Hours, Minutes and Seconds
- 24-Hour Format (military time)
- Visibility of One-Half Second Period
- Provides Calendar: Weekday, Date, Month and Year
- Alarm Intervals are Configurable for Half of a second, One Second, 10 Seconds, One Minute, 10 Minutes, One Hour, One Day, One Week, One Month and One Year
- Alarm Repeat with Decrementing Counter
- Alarm with Indefinite Repeat: Chime
- Year Range: 2000 to 2099
- Leap Year Correction
- BCD Format for Smaller Firmware Overhead
- Optimized for Long-Term Battery Operation
- Fractional Second Synchronization
- User Calibration of the Clock Crystal Frequency with Auto-Adjust
- Uses External 32.768 kHz Crystal, 32 kHz Internal Oscillator, PWRLCLK Input Pin or Peripheral Clock
- Alarm Pulse, Seconds Clock or Internal Clock Output on RTCC Pin

FIGURE 15-1: RTCC BLOCK DIAGRAM



REGISTER 16-7: AD1CHIT: ADC COMPARE HIT REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	CHH<13:8>(1,2)					
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHH<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-14 **Unimplemented:** Read as '0'

bit 13-0 **CHH<13:0>:** ADC Compare Hit bits(1,2)

If CM<1:0> = 11:

1 = ADC Result Buffer x has been written with data or a match has occurred

0 = ADC Result Buffer x has not been written with data

For All Other Values of CM<1:0>:

1 = A match has occurred on ADC Result Channel n

0 = No match has occurred on ADC Result Channel n

Note 1: The CHH<13:11> bits are not implemented in 20-pin devices.

2: The CHH<13:12> bits are not implemented in 28-pin devices.

TABLE 18-1: CLC1 AND CLC2 REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
0A80	CLC1CON	32:16	—	—	—	—	—	—	—	—	—	—	—	—	G4POL	G3POL	G2POL	G1POL	0000
		15:0	ON	—	—	—	INTP	INTN	—	—	LCOE	LCOUT	LCPOL	—	—	MODE<2:0>			0000
0A90	CLC1SEL	32:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	DS4<2:0>			—	DS3<2:0>			—	DS2<2:0>			—	DS1<2:0>			0000
0AA0	CLC1GLS	32:16	G4D4T	G4D4N	G4D3T	G4D3N	G4D2T	G4D2N	G4D1T	G4D1N	G3D4T	G3D4N	G3D3T	G3D3N	G3D2T	G3D2N	G3D1T	G3D1N	0000
		15:0	G2D4T	G2D4N	G2D3T	G2D3N	G2D2T	G2D2N	G2D1T	G2D1N	G1D4T	G1D4N	G1D3T	G1D3N	G1D2T	G1D2N	G1D1T	G1D1N	0000
0B00	CLC2CON	32:16	—	—	—	—	—	—	—	—	—	—	—	—	G4POL	G3POL	G2POL	G1POL	0000
		15:0	ON	—	—	—	INTP	INTN	—	—	LCOE	LCOUT	LCPOL	—	—	MODE<2:0>			0000
0B10	CLC2SEL	32:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	DS4<2:0>			—	DS3<2:0>			—	DS2<2:0>			—	DS1<2:0>			0000
0B20	CLC2GLS	32:16	G4D4T	G4D4N	G4D3T	G4D3N	G4D2T	G4D2N	G4D1T	G4D1N	G3D4T	G3D4N	G3D3T	G3D3N	G3D2T	G3D2N	G3D1T	G3D1N	0000
		15:0	G2D4T	G2D4N	G2D3T	G2D3N	G2D2T	G2D2N	G2D1T	G2D1N	G1D4T	G1D4N	G1D3T	G1D3N	G1D2T	G1D2N	G1D1T	G1D1N	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively.

20.1 CDAC Control Registers

TABLE 20-1: CDAC REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
0980	DAC1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	DACDAT<4:0>					0000
		15:0	ON	—	—	—	—	—	—	DACOE	—	—	—	—	—	—	REFSEL<1:0>		0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: The register in this table has corresponding CLR, SET and INV registers at its virtual address, plus offsets of 0x4, 0x8 and 0xC, respectively.

REGISTER 20-1: DAC1CON: CDAC CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	DACDAT<4:0>				
15:8	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
	ON	—	—	—	—	—	—	DACOE
7:0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
	—	—	—	—	—	—	REFSEL<1:0>	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-21 **Unimplemented:** Read as '0'

bit 20-16 **DACDAT<4:0>:** CDAC Voltage Reference Selection bits

11111 = (DACDAT<4:0> * VREF+/32) or (DACDAT<4:0> * AVDD/32) volts depending on the REFSEL<1:0> bits
•
•
•
00000 = 0.0 volts

bit 15 **ON:** Voltage Reference Enable bit

1 = Voltage reference is enabled
0 = Voltage reference is disabled

bit 14-9 **Unimplemented:** Read as '0'

bit 8 **DACOE:** CDAC Voltage Reference Output Enable bit

1 = Voltage level is output on the CDAC1 pin
0 = Voltage level is disconnected from the CDAC1 pin

bit 7-2 **Unimplemented:** Read as '0'

bit 1-0 **REFSEL<1:0>:** CDAC Voltage Reference Source Select bits

11 = Reference voltage is AVDD
10 = No reference is selected – output is AVSS
01 = Reference voltage is the VREF+ input pin voltage
00 = No reference is selected – output is AVSS

REGISTER 21-1: HLVDCON: HIGH/LOW-VOLTAGE DETECT CONTROL REGISTER (CONTINUED)

bit 3-0 **HLVDL<3:0>:** High/Low-Voltage Detection Limit bits

1111 = External analog input is used (input comes from the LVDIN pin and is compared with 1.2V band gap)
1110 = VDD trip point is 2.11V(1)
1101 = VDD trip point is 2.21V(1)
1100 = VDD trip point is 2.30V(1)
1011 = VDD trip point is 2.40V(1)
1010 = VDD trip point is 2.52V(1)
1001 = VDD trip point is 2.63V(1)
1000 = VDD trip point is 2.82V(1)
0111 = VDD trip point is 2.92V(1)
0110 = VDD trip point is 3.13V(1)
0101 = VDD trip point is 3.44V(1)
0100-0000 = Reserved; do not use

Note 1: The voltage is typical. It is for design guidance only and not tested. Refer to Table 26-13 in **Section 26.0 "Electrical Characteristics"** for minimum and maximum values.

TABLE 26-6: POWER-DOWN CURRENT (I_{PD})(2)

Parameter No.	Typical(1)	Max	Units	Operating Temperature	VDD	Conditions
DC60	134	198	µA	-40°C	2.0V	Sleep with active main voltage regulator (VREGS (PWRCON<0>) = 1, RETEN (PWRCON<1>) =0)
	136	208	µA	+25°C		
	141	217	µA	+85°C		
	139	209	µA	-40°C	3.3V	
	141	217	µA	+25°C		
	143	231	µA	+85°C		
DC61	4.3	11.7	µA	-40°C	2.0V	Sleep with main voltage regulator in Standby mode (VREGS (PWRCON<0>) = 0, RETEN (PWRCON<1>) = 0)
	5.1	15.6	µA	+25°C		
	11.4	34.3	µA	+85°C		
	6.1	16.8	µA	-40°C	3.3V	
	6.9	20.1	µA	+25°C		
	12.7	36.0	µA	+85°C		
DC62	2.3	—	µA	-40°C	2.0V	Sleep with enabled retention voltage regulator (VREGS (PWRCON<0>) = 1, RETEN (PWRCON<1>) = 1, RETVR (FPOR<2>) = 0)
	2.7	—	µA	+25°C		
	5.2	—	µA	+85°C		
	2.3	—	µA	-40°C	3.3V	
	2.7	—	µA	+25°C		
	5.4	—	µA	+85°C		
DC63	0.28	—	µA	-40°C	2.0V	Sleep with enabled retention voltage regulator (VREGS (PWRCON<0>) = 0, RETEN (PWRCON<1>) = 1, RETVR (FPOR<2>) = 0)
	0.44	—	µA	+25°C		
	2.52	—	µA	+85°C		
	0.29	—	µA	-40°C	3.3V	
	0.44	—	µA	+25°C		
	2.62	—	µA	+85°C		

Note 1: Data in the "Typical" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: Base I_{PD} is measured with:

- Oscillator is configured in FRC mode without PLL (FNOSC<2:0> (FOSCSEL<2:0>) = 000)
- OSC2 is configured as I/O in Configuration Words (OSCIOFNC (FOSCSEL<10>) = 1)
- FSCM is disabled (FCKSM<1:0> (FOSCSEL<15:14>) = 00)
- Secondary Oscillator circuits are disabled (SOSCEN (FOSCSEL<6>) = 0 and SOSCSEL (FOSCSEL<12>) = 0)
- Main and low-power BOR circuits are disabled (BOREN<1:0> (FPOR<1:0>) = 00 and LPBOREN (FPOR<3>) = 0)
- Watchdog Timer is disabled (FWDTEN (FWDT<15>) = 0)
- All I/O pins are configured as outputs and driving low
- No peripheral modules are operating or being clocked (defined PMDx bits are all ones)

TABLE 26-8: I/O PIN INPUT SPECIFICATIONS

Operating Conditions: 2.0V ≤ VDD ≤ 3.6V, -40°C ≤ TA ≤ +85°C (unless otherwise stated)							
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage(2)**					
DI10		I/O Pins with ST Buffer	VSS	—	0.2 VDD	V	
DI15		$\overline{\text{MCLR}}$	VSS	—	0.2 VDD	V	
DI16		OSC1/CLKI (XT mode)	VSS	—	0.2 VDD	V	
DI17		OSC1/CLKI (HS mode)	VSS	—	0.2 VDD	V	
	VIH	**Input High Voltage(2)**					
DI20		I/O Pins with ST Buffer:					
		without 5V Tolerance	0.8 VDD	—	VDD	V	
		with 5V Tolerance	0.8 VDD	—	5.5	V	
DI25		$\overline{\text{MCLR}}$	0.8 VDD	—	VDD	V	
DI26		OSCI/CLKI (XT mode)	0.7 VDD	—	VDD	V	
DI27		OSC1/CLKI (HS mode)	0.7 VDD	—	VDD	V	
DI30	ICNPU	**CNPUx Pull-up Current**	—	350	—	µA	VPIN = 0V, VDD = 3.3V
DI30A	ICNPD	**CNPDx Pull-Down Current**	—	300	—	µA	VPIN = 3.3V, VDD = 3.3V
	IIL	**Input Leakage Current**					
DI50		I/O Pins – 5V Tolerant	—	0.1	1.0	µA	VPIN = 3.3V, VDD = 3.3V, pin at high-impedance
DI51		I/O Pins – Not 5V Tolerant	—	0.1	1.0	µA	VPIN = 3.3V, VDD = 3.3V, pin at high-impedance
DI55		$\overline{\text{MCLR}}$	—	0.1	1.0	µA	VPIN = 3.3V, VDD = 3.3V
DI56		OSC1/CLKI	—	0.1	1.0	µA	VPIN = 3.3V, VDD = 3.3V

Note 1: Data in the "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: Refer to Table 1-1 for I/O pin buffer types.

TABLE 26-14: COMPARATOR SPECIFICATIONS

Operating Conditions: 2.0V < VDD < 3.6V, -40°C < TA < +85°C (unless otherwise stated)						
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(2)**	**Max**	**Units**
D300	VIOFF	Input Offset Voltage	-20	—	20	mV
D301	VICM	Input Common-Mode Voltage	AVSS – 0.3V	—	AVDD + 0.3V	V
D307	TRESP(1)	Response Time	—	150	—	ns

Note 1: Measured with one input at VDD/2 and the other transitioning from VSS to VDD.

2: Data in the "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 26-15: VOLTAGE REFERENCE SPECIFICATIONS

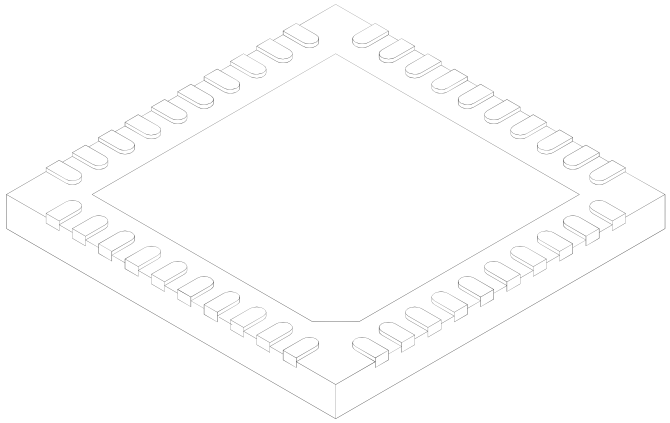
Operating Conditions: 2.0V < VDD < 3.6V, -40°C < TA < +85°C (unless otherwise stated)						
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(2)**	**Max**	**Units**
VRD310	TSET	Settling Time(1)	—	—	10	µs
VRD311	VRA	Accuracy	-1	—	1	LSb
VRD312	VRUR	Unit Resistor Value (R)	—	4.5	—	kΩ

Note 1: Measures the interval while VRDAT<4:0> transitions from '11111' to '00000'.

2: Data in the "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

40-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) – 5x5x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		40	
Pitch	e		0.40 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.127 REF	
Overall Width	E		5.00 BSC	
Exposed Pad Width	E2	3.60	3.70	3.80
Overall Length	D		5.00 BSC	
Exposed Pad Length	D2	3.60	3.70	3.80
Contact Width	b	0.15	0.20	0.25
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-156A Sheet 2 of 2